	CONNECTING CS INDUSTRIES® international and Pan	PC, Bannockb	ourn, Illinois. A	All rights reserved u ntions.	under both	This docume level parts, t	ent is a declaration	tion of t encomp	he substances basses all low	within the er level mat	manufactur erials for wl	er listed it hich the m	em. Note: if anufacturer	f the item is an as has engineering	ssembly with lowe responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information						
Supplie	r Information															
Company name* Company unique I				ique ID	le ID Uni-			Unique ID Authority					Response Date*			
nsemi												2025-06-07				
Contact N	lame		Title - Contact				Phone - Contact*				Email - Contact*					
Product-l	Env-Stewards		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*		Title - Representative				Phone - Representative*				Email - Representative*					
Product-	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	te Version Manufacturing Site		V	Veight*	UOM	Unit Type			
	FQP50N06		06L	JL QF 60V 21mohm L TO220			2025-06-07			CP8		2	030.181	mg	Each	
/Ianufa	cturing Proccess Informat	tion														
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020		J-STD-020 MSI	L Rating	Peak Process Body Tempera		ure Max Time at Peak Tem		Temperate	ire Numb	er of Reflow Cyc	cles		
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30		second	ls 3						
omments	8															
or more	information regarding material	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.81	mg	Supplier	Silicon (Si)	7440-21-3		2.81	mg
Die Attach	1.111	mg	Supplier	Silver (Ag)	7440-22-4		0.0167	mg
			А	Lead (Pb)	7439-92-1	7a	1.0388	mg
			Supplier	Tin (Sn)	7440-31-5		0.0555	mg
Lead Frame	1492.12	mg	В	Nickel (Ni)	7440-02-0		0.1492	mg
			Supplier	Iron (Fe)	7439-89-6		1.4921	mg
			Supplier	Copper (Cu)	7440-50-8		1490.031	mg
			Supplier	Phosphorus (P)	7723-14-0		0.4476	mg
Mold Compound-Black	518.4	mg		Proprietary	proprietary data		25.92	mg
			Supplier	Carbon Black (C)	1333-86-4		2.592	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		386.208	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		77.76	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		25.92	mg
Plating	13.3	mg	Supplier	Tin (Sn)	7440-31-5		13.3	mg
Wire Bond - Al	2.44	mg	Supplier	Aluminum (Al)	7429-90-5		2.44	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signa range of distribution unless otherwise noted).